

# MOSFET - Power, Single N-Channel, TOLL 60 V, 0.75 mΩ, 470 A

# **NVBLS0D7N06C**

#### **Features**

- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- Lowers Switching Noise/EMI
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	60	V
Gate-to-Source Voltage	€		V <sub>GS</sub>	±20	V
Continuous Drain		T <sub>C</sub> = 25°C	I <sub>D</sub>	470	Α
Current R <sub>0JC</sub> (Note 2)	Steady	T <sub>C</sub> = 100°C		332	
Power Dissipation	State	T <sub>C</sub> = 25°C	$P_{D}$	314	W
R <sub>θJC</sub> (Note 2)		T <sub>C</sub> = 100°C		157	
Continuous Drain		T <sub>A</sub> = 25°C	I <sub>D</sub>	54	Α
Current $R_{\theta JA}$ (Notes 1, 2)	Steady	T <sub>A</sub> = 100°C	1	38	
Power Dissipation	State	T <sub>A</sub> = 25°C	$P_{D}$	4.2	W
R <sub>θJA</sub> (Notes 1, 2)		T <sub>A</sub> = 100°C		2.1	
Pulsed Drain Current	$T_A = 25$	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	900	Α
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode)			I <sub>S</sub>	260	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 40 A)			E <sub>AS</sub>	800	mJ
Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

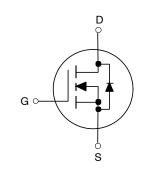
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	0.48	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	36	

- 1. Surface-mounted on FR4 board using a 1 in<sup>2</sup> pad size, 2 oz. Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
60 V	0.75 mΩ @ 10 V	470 A





H-PSOF8L CASE 100CU

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NVBLS0D7N06C	H-PSOF8L (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. ELECTRICAL CHARACTERISTICS ( $T_J$  = 25°C unless otherwise noted)

Parameter	Symbol	Test Cond	litions	Min	Тур	Max	Units
OFF CHARACTERISTICS	•			•			•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$I_D = 250 \mu A, V_{GS} = 0 V$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 661 μA, ref to 25°C			26.5		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	T <sub>J</sub> = 25°C			10	μΑ
			T <sub>J</sub> = 125°C			100	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>0</sub>	<sub>GS</sub> = 20 V			100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{GS} = V_{DS}, I_{D}$	= 661 μΑ	2.0	2.8	4.0	V
Negative Threshold Temperature Coefficient	V <sub>GS(th)</sub> /T <sub>J</sub>	I <sub>D</sub> = 661 μA, r	ef to 25°C		9.8		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V,	I <sub>D</sub> = 80 A		0.56	0.75	mΩ
Forward Transconductance	9FS	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 80 A			310		S
CHARGES & CAPACTIANCES				-			
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 30 \text{ V}, f = 10 \text{ kHz}$			13730		pF
Output Capacitance	C <sub>oss</sub>				6912		pF
Reverse Transfer Capacitance	C <sub>rss</sub>				92		pF
Total Gate Charge	Q <sub>G(tot)</sub>	$V_{GS} = 10 \text{ V}, V_{DS} = 30 \text{ V},$ $I_{D} = 80 \text{ A}$			170		nC
Threshold Gate Charge	Q <sub>G(th)</sub>				39		nC
Gate-to-Source Charge	$Q_{gs}$				62		nC
Gate-to-Drain Charge	$Q_{gd}$				16		nC
SWITCHING CHARACTERISTICS, V <sub>GS</sub> = 10	<b>V</b> (Note 3)						
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 30 V, $I_{D}$ = 80 A, $R_{G}$ = 6 $\Omega$			37		ns
Rise Time	t <sub>r</sub>	I <sub>D</sub> = 80 A, H	$G = 6 \Omega$		57		ns
Turn-Off Delay Time	t <sub>d(off)</sub>				146		ns
Fall Time	t <sub>f</sub>				105		ns
DRAIN-SOURCE DIODE CHARACTERIST	cs				-		-
Forward Diode Voltage	$V_{SD}$	I <sub>S</sub> = 80 A, V <sub>GS</sub> = 0 V	T <sub>J</sub> = 25°C		0.79	1.2	V
		I <sub>S</sub> = 80 A, V <sub>GS</sub> = 0 V T <sub>J</sub> =	T <sub>J</sub> = 125°C		0.66		V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0 \text{ V, } dI_S/d_t = 100 \text{ A/}\mu\text{s,}$ $I_S = 66 \text{ A}$			132		ns
Charge Time	t <sub>a</sub>				64		ns
Discharge Time	t <sub>b</sub>				68		ns
Reverse Recovery Charge	Q <sub>rr</sub>				386		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures

#### **TYPICAL CHARACTERISTICS**

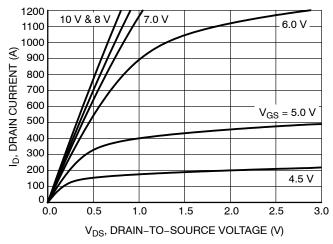


Figure 1. On-Region Characteristics

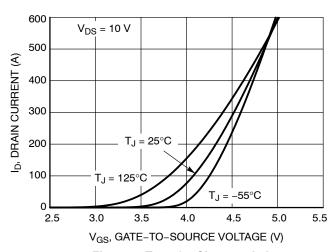


Figure 2. Transfer Characteristics

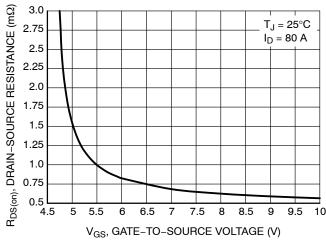


Figure 3. On-Resistance vs. V<sub>GS</sub>

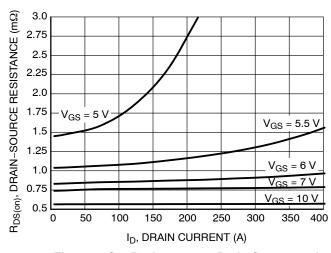


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

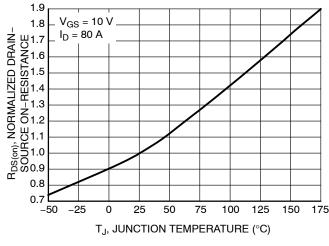


Figure 5. On–Resistance Variation with Temperature

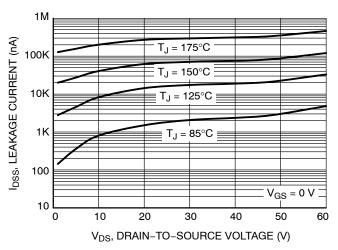


Figure 6. Drain-to-Source Leakage Current vs. Voltage

#### **TYPICAL CHARACTERISTICS**

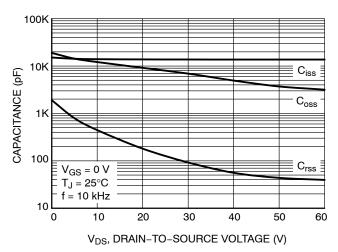


Figure 7. Capacitance Variation

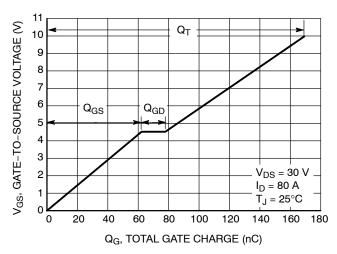


Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

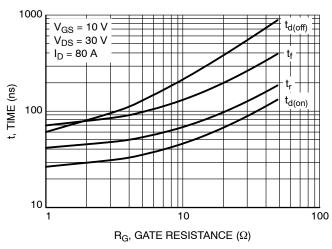


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

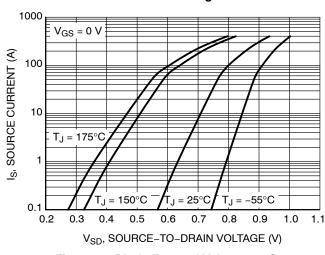


Figure 10. Diode Forward Voltage vs. Current

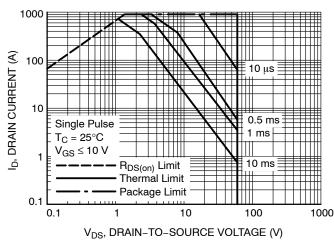


Figure 11. Maximum Rated Forward Biased Safe Operating Area

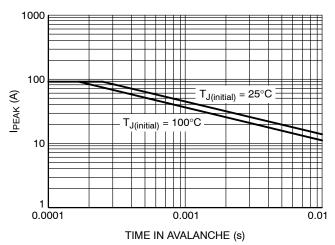


Figure 12. I<sub>PEAK</sub> vs. Time in Avalanche

## **TYPICAL CHARACTERISTICS**

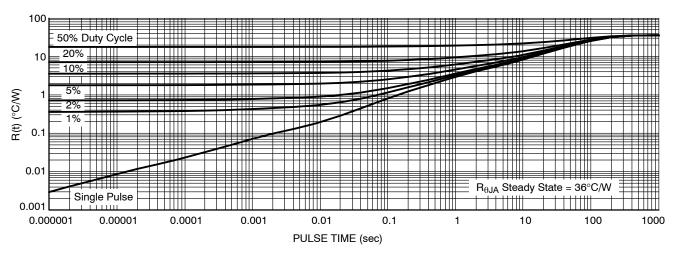
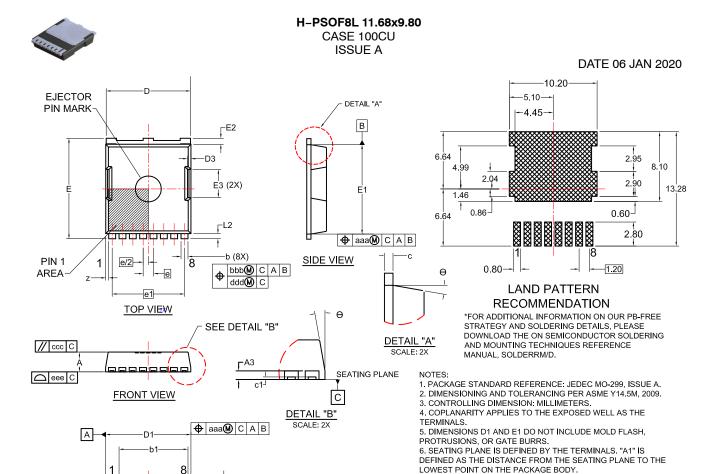


Figure 13. Thermal Characteristics (Junction-to-Ambient)



DIM	MILLIMETERS			
5	MIN.	NOM.	MAX.	
Α	2.20	2.30	2.40	
A3	0.40	0.50	0.60	
b	0.70	0.80	0.90	
b1		8.00 REF	-	
С	0.40	0.50	0.60	
c1	0.10			
D	9.70	9.80	9.90	
D1	9.80	9.90	10.00	
D2	4.73 BSC			
D3	0.40 REF			
D4	3.75 BSC			
D5	_	1.20		
D6	7.40	7.50	7.60	
D7	(8.30)			
E	11.58	11.68	11.78	
E1	10.28	10.38	10.48	
E2	0.60	0.70	0.80	
E3	3.30 REF			

E4

DIM	MILLIMETERS				
Divi	MIN.	NOM.	MAX.		
е	1.20 BSC				
e/2	(	0.60 BSC	;		
e1		3.40 BSC	;		
K	1.50	1.57	1.70		
L	1.90	2.00	2.10		
L2	0.50	0.60	0.70		
Z	0.35 REF				
θ	0°		12°		
aaa	0.20				
bbb	0.25				
ccc	0.20				
ddd	0.20				
eee		0.10			
E5	-	3.30	_		
E6		0.65	_		
E7	7.15 REF				
E8	6.55	6.65	6.75		
E9	5.89 BSC				
E10	5.19 BSC				

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

2.60

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H.A.A.A.A.A.A

|--D5 (3X)

D4 -

-D7

**BOTTOM VIEW** 

E10

E9

| E8

L

-0.10 E4 (2X)

E5 (2X) ⊢E6 (2X)

Α

WW

ZΖ

GENERIC
MARKING DIAGRAM\*

AYWWZZ

XXXXXXXX

= Year

= Work Week

XXXX = Specific Device Code

= Assembly Location

= Assembly Lot Code

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